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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: William James Palmteer and Philip Joseph Beucler

Application No.: 09/966,222

Examiner: Unassigned

Filed: September 28, 2001

Group Art Unit: Unassigned

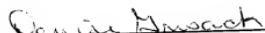
Docket No.: 17658

Title: IMPROVED LEADFRAME-BASED CHIP SCALE PACKAGE

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service on January 18, 2002, in an envelope as First Class Mail, postage prepaid, addressed to: Commissioner for Patents, Washington, D.C. 20231,
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Commissioner for Patents
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Sir:

Applicant encloses herewith three (3) sheets of formal drawings (Figures 1A through 3) relating to the above-identified patent application.

On the back of the enclosed drawings are: the Name of the first named inventor, the

Application No. 09/966,222

Docket No. 17658 USA

Application No., and the attorney's name and phone number.

Please charge any comparison fees to Synnestvedt & Lechner's Deposit Account No. 19-

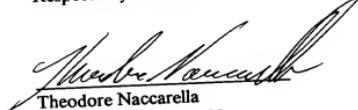
5425. Copies of this Transmittal Letter are attached in duplicate.

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Respectfully submitted,



Theodore Naccarella
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Dated: 1.18.02

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Enclosures

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